01

Part Information

01 Part Information

(1) Design Record of The Target Product

New Point Overview

Technical aspect	New part X	Comparison Part Y	Comparison Part Z	Technical level
Elements	Flash(MONOS)	Flash(Floating Gate)	Flash(Floating Gate)	New

- New Technology etc.

02

New Points And Details of Assessment

01 Part Information

(1) Design Record of The Target Product

Background of New Part Development

- New part X applies new technology △△△ to achieve ***.
- For _ _ _, we use ◇◇◇, which has a proven track record.

- Part features
- Part roadmap, part lineup
- New technology overview, etc.

01 Part Information

(1) Design Record of The Target Product

Overview of The Company / Factory Responsible for The Process

(a) Wafer Process: Company A, Factory OO

Mass production of the Z series of Parts has been started since the yyyy/mm month.
Mass production is about xxM units.

Company name	Company A, Factory OO
Location	(City) / (Country)
Foundation	yyyy
Business Outline	Wafer Fabrication
Quality System Certification	ISO9002 (in yyyy) ISO14001 (in yyyy) IATF16949(in yyyy)

02 New Points And Details of Assessment

- Manufacturing Technology Survey Sheet -

Part Outline etc. : Section a)

		Section a)			
	Supplier Name	Company A	Company A	Company A	Reference info
Product Description	Product Description	New Product X	New Product Y	New Product Z	--
	Product Name (Product Family)	Product Family X	Product Family Y	Product Family Z	--
	Operating Temperature	□a: -40~125℃	□a: -40~125℃	□a: -40~105℃	--
	Maximum Operating Frequency	xxxMHz	xxxMHz	xxxMHz	--
	Process / Design Rule	CMOS/ xxx nm	CMOS/ xxx nm	CMOS/ xxx nm	--
	Package Type	QFP	QFP	QFP	--
	Number of Transistor	100	100	100	--
	Total Chip count (if multi tip module)	1	1	1	--
	Configuration	--	--	--	--
Manufacturing Site	Front end site (Name / Location) QMS certification (valid until)	Factory OO, Japan IATF16949(20yy.mm)	Factory OO, Japan IATF16949(20yy.mm)	Factory OO, Japan IATF16949(20yy.mm)	--
	Back end site (Name / Location) QMS certification (valid until)	Factory △△, Japan IATF16949(20yy.mm)	Factory △△, Japan IATF16949(20yy.mm)	Factory △△, Japan IATF16949(20yy.mm)	--
	Test site (Name / Location) QMS certification (valid until)	Factory △△, Japan IATF16949(20yy.mm)	Factory △△, Japan IATF16949(20yy.mm)	Factory △△, Japan IATF16949(20yy.mm)	--
Quality Grade, Performance	Target failure rate	□ ppm	□ ppm	□ ppm	--
	Gade	AEC-Q100 Grade 1	AEC-Q100 Grade 1	AEC-Q100 Grade 2	--
	MSL	MSL3	MSL3	MSL3	--
	Production start timing	mmm, 20yy (Plan)	mmm, 20yy (Plan)	mmm, 20yy (Plan)	--
	Production volume cumulated		yy Mpcs (family total)	zz Mpcs (family total)	--

01 Part Information

(1) Design Record of The Target Part

The Target Part

Part name	New Part X	Comparison Part Y	Comparison Part Z
Part Name or Series (Process) Name	xxxxxxxxxxxx	yyyyyyyyyyyy	zzzzzzzzzzzz
Operating Temperature Range	Ta= -40~125℃	Ta= -40~125℃	Ta= -40~125℃
Maximum Operating Frequency	xxxMHz	xxxMHz	xxxMHz
Process / Design rule	CMOS/ xxx nm	CMOS/ xxx nm	CMOS/ xxx nm
PKG type (QFP, BGA, etc.)	QFP	QFP	QFP
Number of pins	100	100	100
Wafer Factory	Company A, Factory OO	Company A, Factory OO	Company A, Factory OO
Assembly Factory	Company A, Factory △△	Company A, Factory △△	Company A, Factory △△
Temperature Grade	AEC-Q100 Grade 1	AEC-Q100 Grade 1	AEC-Q100 Grade 1
MSL	MSL3	MSL3	MSL3

01 Part Information

(1) Design Record of The Target Product

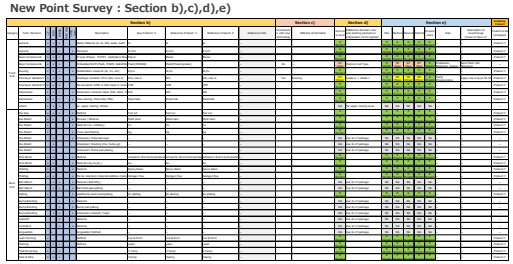
Overview of The Company / Factory Responsible for The Process

(b) Assembly/Test Process : Company A, Factory △△

Mass production of in-vehicle parts (parts of other semiconductor maker) started in yyyy/mm month.
Mass production is about xxM units.

Company name	Company A, Factory △△
Location	(City) / (Country)
Foundation	Yyyy
Business Outline	Semiconductor Assembly, Chip probing, Final testing
Quality System Certification	ISO9002 (in yyyy) ISO14001 (in yyyy) IATF16949(in yyyy)

02 New Points And Details of Assessment

- Manufacturing Technology Survey Sheet -

New Point Survey : Section b),c),d),e)